

Nanopackaging Errata

Chapter 4

Figure 4.7 (change λ)

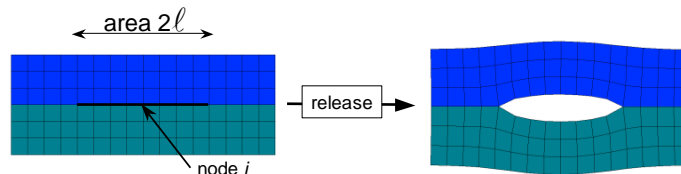


Fig 4.14 caption: “The contours indicate the damage value in the cohesive zone elements: a black color corresponds to a value of 1.00, i.e. a crack.”

Below Equation 4.12:

$$\text{If } \Lambda \ll a ,$$

Chapter 5

Page 99

Correct equation is:

$$\frac{X^n}{r^m} = A(T)t$$

Chapter 10

Page 204

First half of first sentence in Section 10.3.4 is missing

Sumitomo Electric recently developed a new-concept ACF using nickel nano particles with a straight-chain-like structure as conductive fillers [54].

Chapter 20

Page 451 Correct figure is:

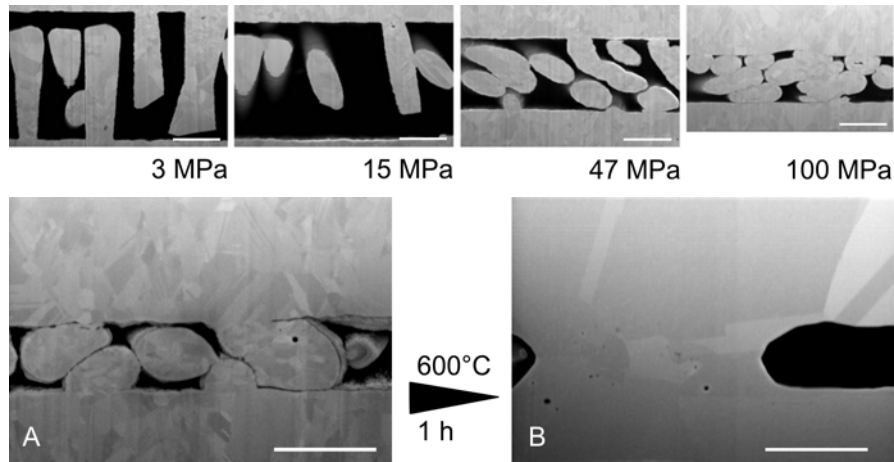


Fig. 20.4. FIB dissections of intercalated wire decorated surfaces (all gold), using flip-chip bonding principle. Bonding at ambient temperature with pressure as indicated. A: Close-up for 100 MPa sample. B: Intergrain diffusion and contact formation after annealing. All scale bars: 1 μm.

Chapter 22

Page 498 Correct figure is:

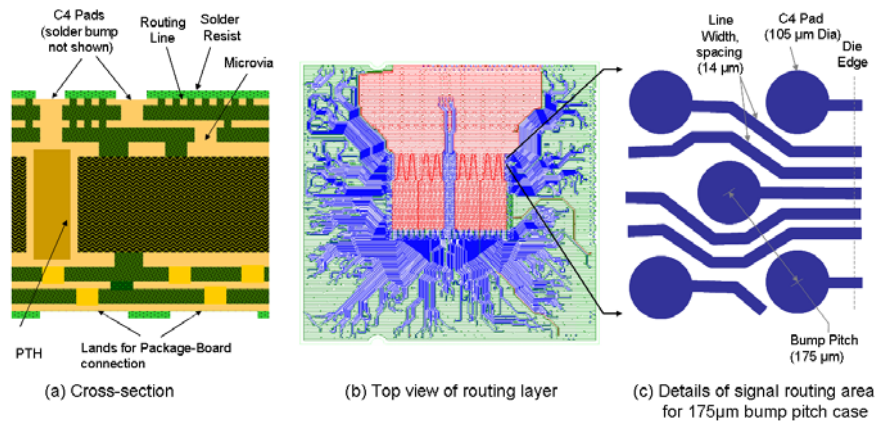


Fig. 22.8 Sketch of a typical organic flip chip package substrate.



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